



Material Content Data Sheet



Sales Product Name		ESD108-B1-CSP0201 E6327		Issued		19. July 2018		
MA#		MA001126876						
Package		SG-WLL-2-1		Weight*		0.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.063	94.60	94.60	945916	945916
pad	inorganic material	phosphorus	7723-14-0	0.000	0.09		857	
	noble metal	gold	7440-57-5	0.000	0.09		902	
	non noble metal	copper	7440-50-8	0.000	0.00		30	
	inorganic material	silicon	7440-21-3	0.000	0.00		15	
	non noble metal	aluminium	7429-90-5	0.000	0.34		3443	
	noble metal	palladium	7440-05-3	0.000	0.56		5623	
	non noble metal	nickel	7440-02-0	0.003	4.13	5.21	41289	52159
passivation	inorganic material	SiO2	60676-86-0	0.000	0.07		692	
	inorganic material	Si3N4	12033-89-5	0.000	0.12	0.19	1233	1925
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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